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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c64a-04-pq

PIC16C6X

4.2.2.2 OPTION REGISTER

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external INT interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 4-10: OPTION REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7						bit0	

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **RBPU**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

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FIGURE 4-19: PIR1 REGISTER FOR PIC16C65/65A/R65/67 (ADDRESS 0Ch)

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIF	—	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **PSPIF**: Parallel Slave Port Interrupt Flag bit
1 = A read or a write operation has taken place (must be cleared in software)
0 = No read or write operation has taken place

bit 6: **Reserved**: Always maintain this bit clear.

bit 5: **RCIF**: USART Receive Interrupt Flag bit
1 = The USART receive buffer is full (cleared by reading RCREG)
0 = The USART receive buffer is empty

bit 4: **TXIF**: USART Transmit Interrupt Flag bit
1 = The USART transmit buffer is empty (cleared by writing to TXREG)
0 = The USART transmit buffer is full

bit 3: **SSPIF**: Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflow occurred (must be cleared in software)
0 = No TMR1 register overflow occurred

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

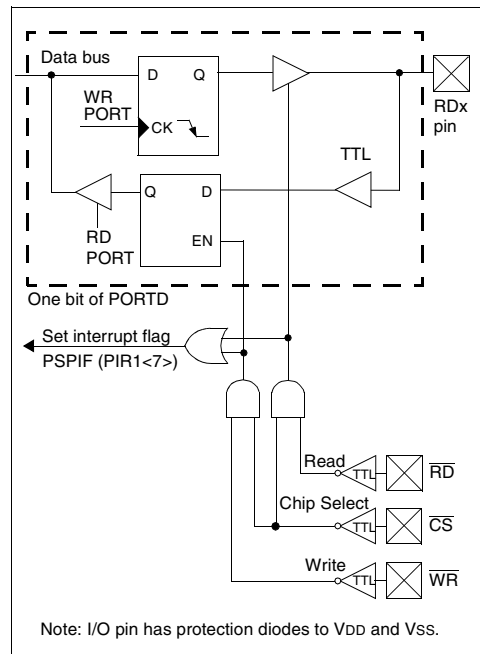
Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

It can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting PSPMODE enables port pin RE0/ \overline{RD} to be the \overline{RD} input, RE1/ \overline{WR} to be the \overline{WR} input and RE2/ \overline{CS} to be the \overline{CS} (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (set).

A write to the PSP occurs when both the \overline{CS} and \overline{WR} lines are first detected low. When either the \overline{CS} or \overline{WR} lines become high (level triggered), then the Input Buffer Full status flag bit IBF (TRISE<7>) is set on the Q4 clock cycle, following the next Q2 cycle, to signal the write is complete (Figure 5-12). The interrupt flag bit PSPIF (PIR1<7>) is also set on the same Q4 clock cycle. IBF can only be cleared by reading the PORTD input latch. The input Buffer Overflow status flag bit IBOV (TRISE<5>) is set if a second write to the Parallel Slave Port is attempted when the previous byte has not been read out of the buffer.

When not in Parallel Slave Port mode, the IBF and OBF bits are held clear. However, if flag bit IBOV was previously set, it must be cleared in firmware.

FIGURE 5-11: PORTD AND PORTE AS A PARALLEL SLAVE PORT



Steps to follow when setting up an Asynchronous Reception:

1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, set bit BRGH (Section 12.1).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, then set enable bit RCIE.
4. If 9-bit reception is desired, then set bit RX9.
5. Enable the reception by setting enable bit CREN.
6. Flag bit RCIF will be set when reception is complete, and an interrupt will be generated if enable bit RCIE was set.
7. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading the RCREG register.
9. If any error occurred, clear the error by clearing enable bit CREN.

TABLE 12-7: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Reception.

Note 1: PSPIE and PSPIF are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIE1<6> and PIR1<6> are reserved, always maintain these bits clear.

PIC16C6X

FIGURE 13-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 1

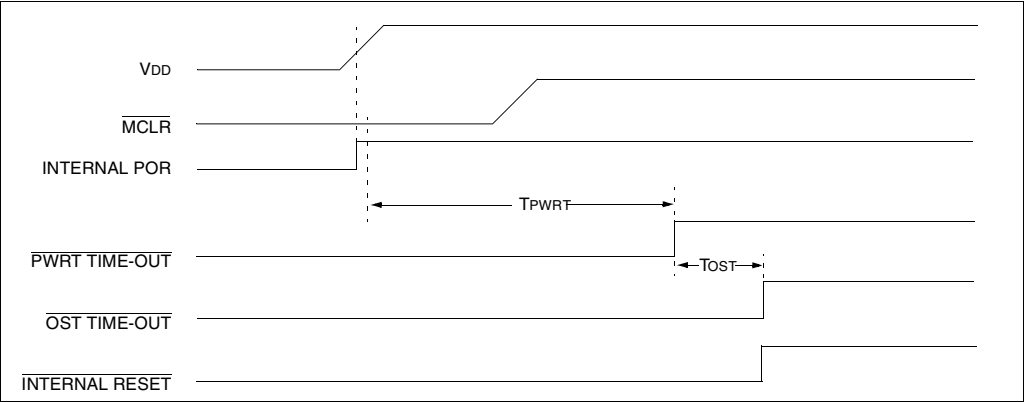


FIGURE 13-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 2

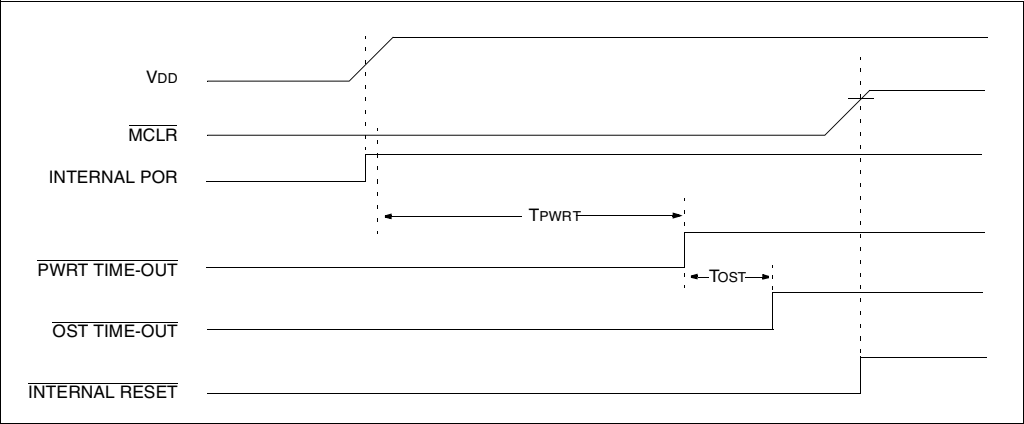
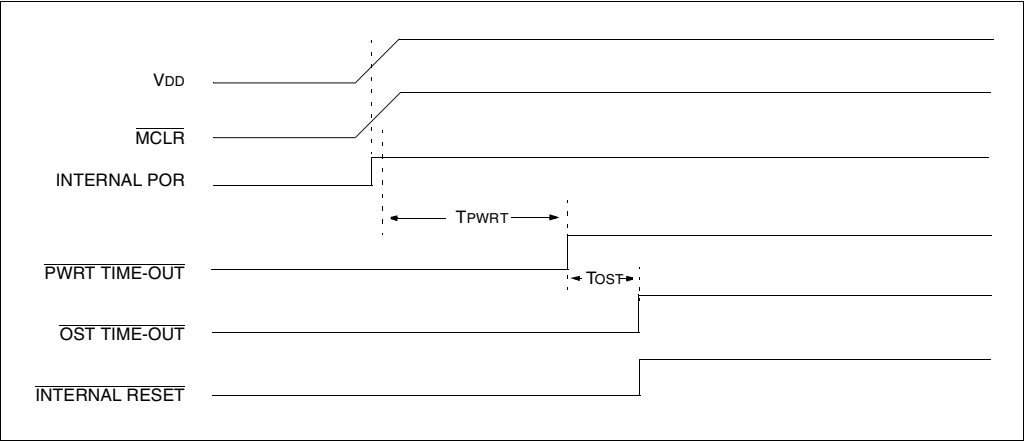


FIGURE 13-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})



PIC16C6X

TABLE 14-2: PIC16CXX INSTRUCTION SET

Mnemonic, Operands	Description	Cycles	14-Bit Opcode			Status Affected	Notes	
			MSb	LSb				
BYTE-ORIENTED FILE REGISTER OPERATIONS								
ADDWF	f, d	Add W and f	1	00	0111	dfff ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	1fff ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff ffff	Z	1,2
DECf	f, d	Decrement f	1	00	0011	dfff ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	1fff ffff		
NOP	-	No Operation	1	00	0000	0xx0 0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS								
BCF	f, b	Bit Clear f	1	01	00bb	bfff ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff ffff		3
LITERAL AND CONTROL OPERATIONS								
ADDLW	k	Add literal and W	1	11	111x	kkkk kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk kkkk		
CLRWDt	-	Clear Watchdog Timer	1	00	0000	0110 0100	$\overline{TO}, \overline{PD}$	
GOTO	k	Go to address	2	10	1kkk	kkkk kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000 1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000 1000		
SLEEP	-	Go into standby mode	1	00	0000	0110 0011	$\overline{TO}, \overline{PD}$	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk kkkk	Z	

- Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.
- 2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.
- 3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

PIC16C6X

BCF		Bit Clear f			
Syntax:	[label] BCF f,b				
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7				
Operation:	0 → (f)				
Status Affected:	None				
Encoding:	01	00bb	bfff	ffff	
Description:	Bit 'b' in register 'f' is cleared.				
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write register 'f'	

Example BCF FLAG_REG, 7

Before Instruction
FLAG_REG = 0x07
After Instruction
FLAG_REG = 0x47

BTFSC		Bit Test, Skip if Clear						
Syntax:	[label] BTFSC f,b							
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7							
Operation:	skip if (f) = 0							
Status Affected:	None							
Encoding:	<table border="1"><tr><td>01</td><td>10bb</td><td>bfff</td><td>ffff</td></tr></table>				01	10bb	bfff	ffff
01	10bb	bfff	ffff					
Description:	If bit 'b' in register 'f' is '1' then the next instruction is executed. If bit 'b', in register 'f', is '0' then the next instruction is discarded, and a NOP is executed instead, making this a 2TCy instruction.							
Words:	1							
Cycles:	1(2)							
Q Cycle Activity:	Q1	Q2	Q3	Q4				

If Skip: (2nd Cycle)

Q1	Q2	Q3	Q4
No-Operation	No-Operation	No-Operation	No-Operation

Example

```

HERE      BTFSC      FLAG,1
FALSE      GOTO      PROCESS_CODE
TRUE      •
            •
            •

```

Before Instruction
PC = address HERE

After Instruction
if FLAG<1> = 0,
PC = address TRUE
if FLAG<1>=1,
PC = address FALSE

BSF		Bit Set f			
Syntax:	[label] BSF f,b				
Operands:	$0 \leq f \leq 127$ $0 \leq b \leq 7$				
Operation:	$1 \rightarrow (f)$				
Status Affected:	None				
Encoding:	01	01bb	bfff	ffff	
Description:	Bit 'b' in register 'f' is set.				
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write register 'f'	

Example BSF FLAG_REG, 7

Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 15-5: TIMER0 EXTERNAL CLOCK TIMINGS

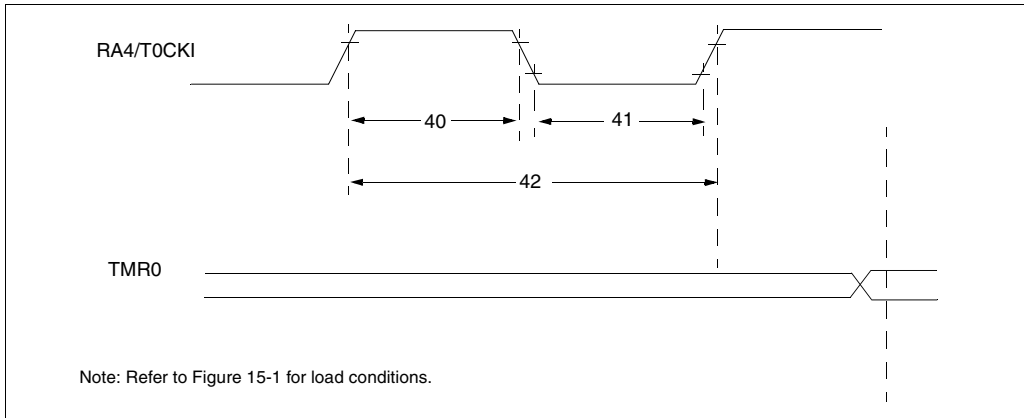


TABLE 15-5: TIMER0 EXTERNAL CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period	No Prescaler	$T_{CY} + 40$	—	—	ns	N = prescale value (2, 4, ..., 256)
			With Prescaler	Greater of: 20 ns or $\frac{T_{CY} + 40}{N}$	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated)					
		Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
		Operating voltage VDD range as described in DC spec Section 17.1 and Section 17.2					
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
D100	Capacitive Loading Specs on Output Pins						
	OSC2 pin	COSC2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF	
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.
- 2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.

DC CHARACTERISTICS <div> Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 18.1 and Section 18.2 </div>							
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
D090	Output High Voltage I/O ports (Note 3)	VOH	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D150*	Open-Drain High Voltage	VOD	-	-	14	V	RA4 pin
D100	Capacitive Loading Specs on Output Pins OSC2 pin	COSC2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF	
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

- The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- Negative current is defined as current sourced by the pin.

18.5 Timing Diagrams and Specifications

FIGURE 18-2: EXTERNAL CLOCK TIMING

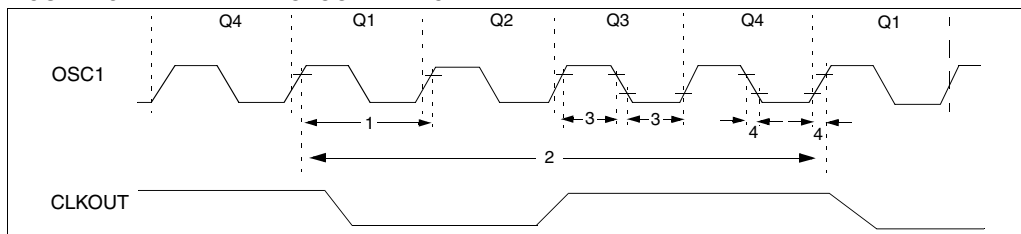


TABLE 18-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
			5	—	—	μs	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
2	Tcy	Instruction Cycle Time (Note 1)	200	Tcy	DC	ns	Tcy = 4/Fosc
			200	Tcy	DC	ns	Tcy = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 18-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

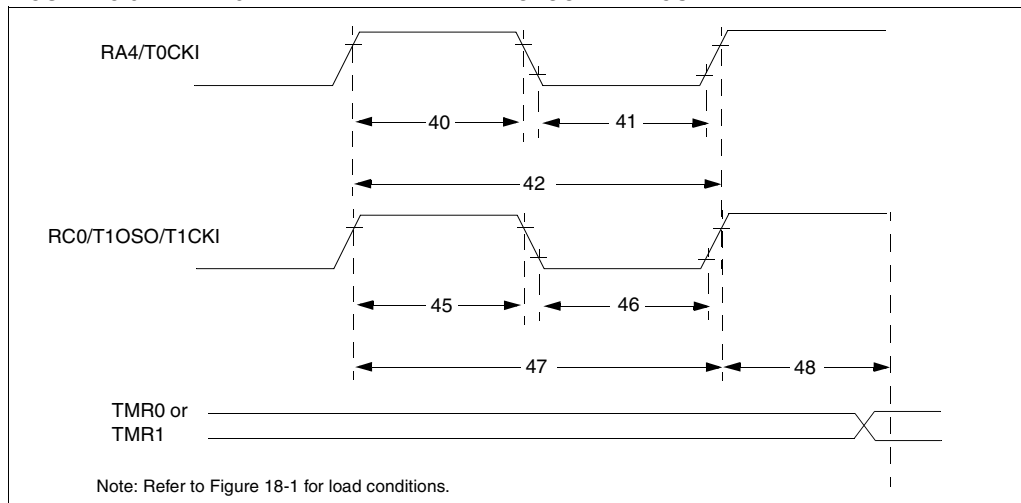


TABLE 18-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period	No Prescaler	$T_{CY} + 40$	—	—	ns	
			With Prescaler	Greater of: 20 or $T_{CY} + 40$ N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2, 4, 8	PIC16C6X 15 PIC16LC6X 25	—	—	ns	
			Asynchronous	PIC16C6X 30 PIC16LC6X 50	—	—	ns	
					—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2, 4, 8	PIC16C6X 15 PIC16LC6X 25	—	—	ns	
			Asynchronous	PIC16C6X 30 PIC16LC6X 50	—	—	ns	
					—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16C6X Greater of: 30 OR $T_{CY} + 40$ N PIC16LC6X Greater of: 50 OR $T_{CY} + 40$ N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16C6X 60 PIC16LC6X 100	—	—	ns	N = prescale value (1, 2, 4, 8)
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)		DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment		$2T_{osc}$	—	$7T_{osc}$	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

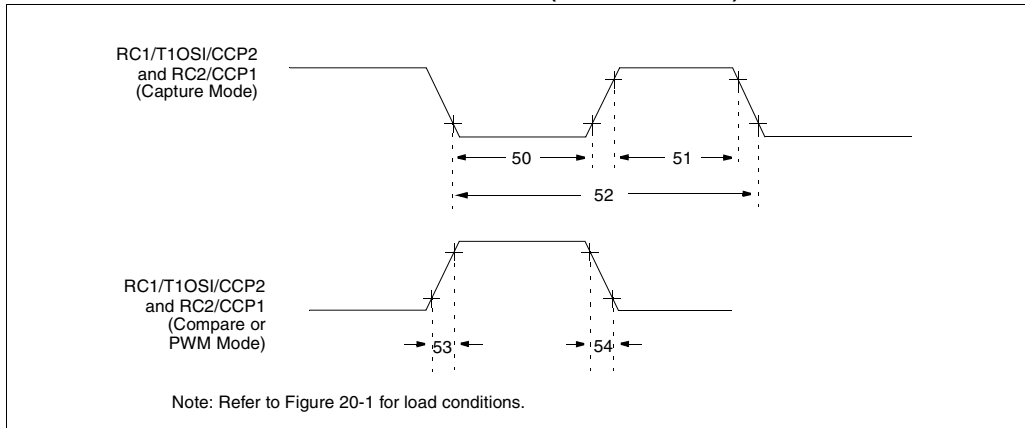


TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C63/65A	10	—	ns	
				PIC16LC63/65A	20	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C63/65A	10	—	ns	
				PIC16LC63/65A	20	—	ns	
52*	TccP	CCP1 and CCP2 input period		$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4, or 16)
53*	TccR	CCP1 and CCP2 output rise time	PIC16C63/65A	—	10	25	ns	
			PIC16LC63/65A	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time	PIC16C63/65A	—	10	25	ns	
			PIC16LC63/65A	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

21.1 DC Characteristics: PIC16CR63/R65-04 (Commercial, Industrial) PIC16CR63/R65-10 (Commercial, Industrial) PIC16CR63/R65-20 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS							
Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	-	5.5 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5	mA	XT, RC, osc config FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013				10	20	mA	HS osc config FOSC = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020 D021 D021A	Power-down Current (Note 3, 5)	IPD	-	10.5	42	μA	VDD = 4.0V, WDT enabled, -40°C to +85°C
				1.5	16	μA	VDD = 4.0V, WDT disabled, -0°C to +70°C
				1.5	19	μA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD, MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = VDD/2R_{ext}$ (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 21-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

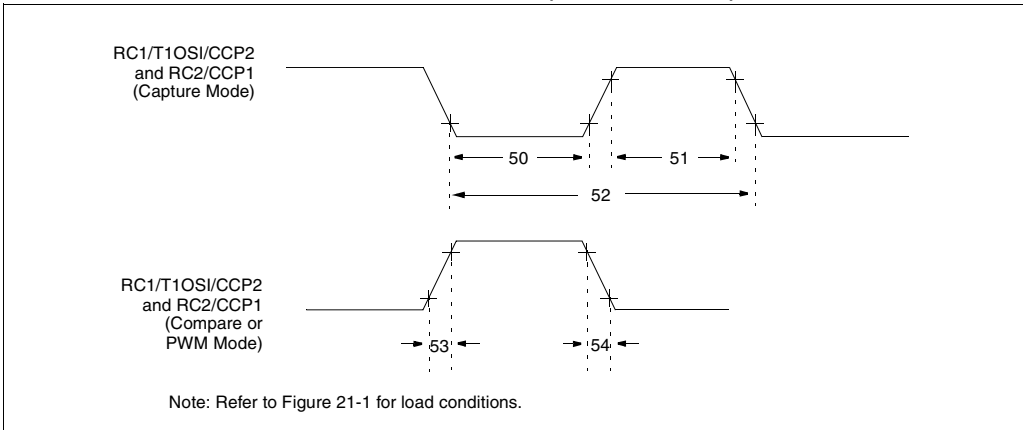


TABLE 21-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16CR63/R65	10	—	ns	
				PIC16LCR63/R65	20	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16CR63/R65	10	—	ns	
				PIC16LCR63/R65	20	—	ns	
52*	TccP	CCP1 and CCP2 input period		$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4, or 16)
53*	TccR	CCP1 and CCP2 output rise time		PIC16CR63/R65	10	25	ns	
				PIC16LCR63/R65	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16CR63/R65	10	25	ns	
				PIC16LCR63/R65	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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FIGURE 23-14: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

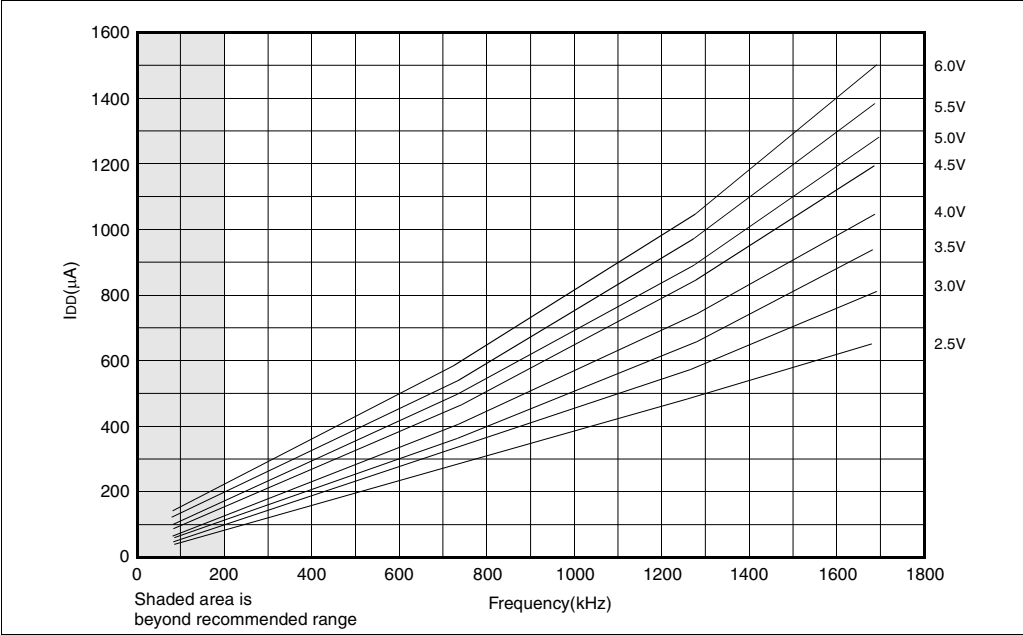
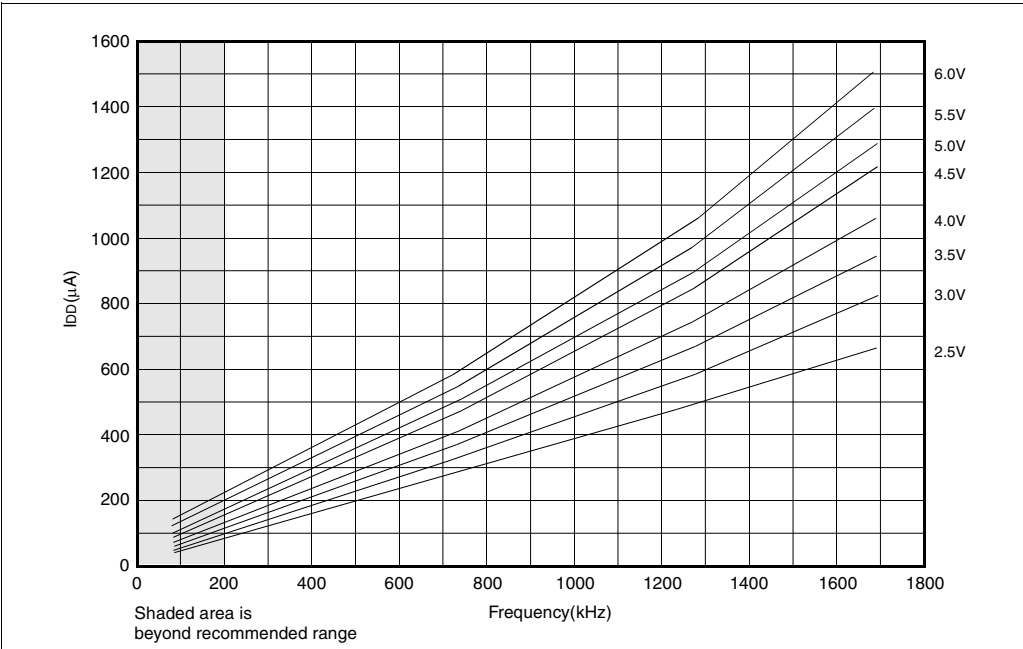


FIGURE 23-15: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)

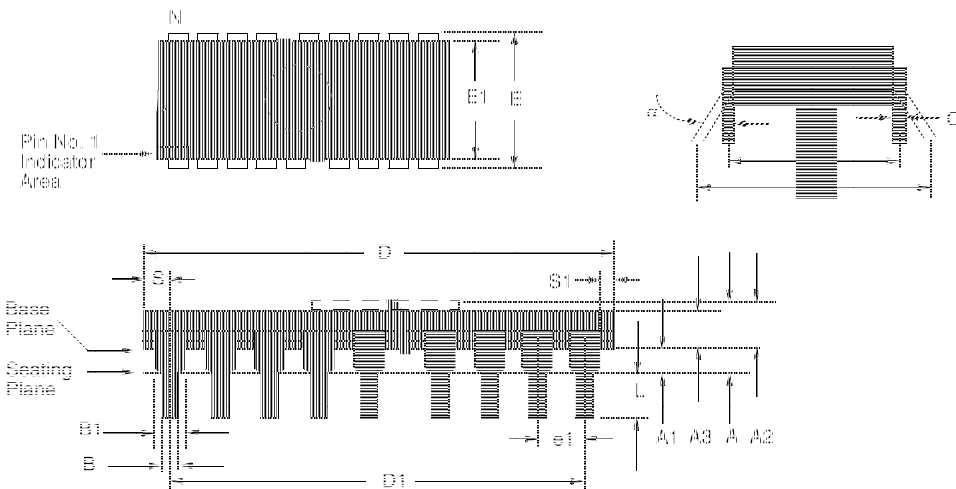


Data based on matrix samples. See first page of this section for details.

PIC16C6X

24.8 40-Lead Ceramic Cerdip Dual In-line with Window (600 mil) (JW)

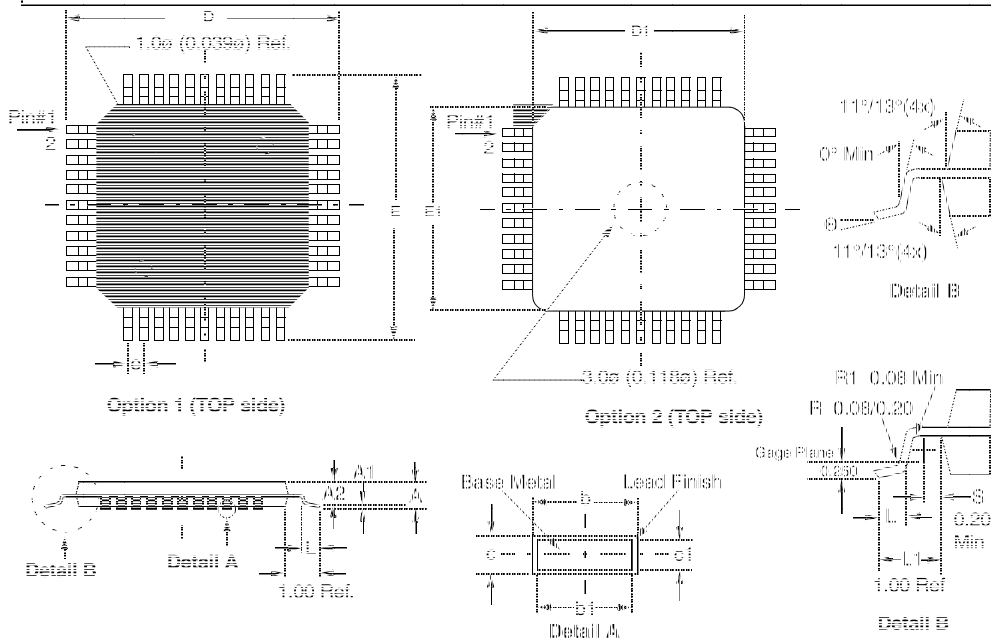
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Package Group: Ceramic Cerdip Dual In-Line (CDP)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	4.318	5.715		0.170	0.225	
A1	0.381	1.778		0.015	0.070	
A2	3.810	4.699		0.150	0.185	
A3	3.810	4.445		0.150	0.175	
B	0.355	0.585		0.014	0.023	
B1	1.270	1.651	Typical	0.050	0.065	Typical
C	0.203	0.381	Typical	0.008	0.015	Typical
D	51.435	52.705		2.025	2.075	
D1	48.260	48.260	Reference	1.900	1.900	Reference
E	15.240	15.875		0.600	0.625	
E1	12.954	15.240		0.510	0.600	
e1	2.540	2.540	Reference	0.100	0.100	Reference
eA	14.986	16.002	Typical	0.590	0.630	Typical
eB	15.240	18.034		0.600	0.710	
L	3.175	3.810		0.125	0.150	
N	40	40		40	40	
S	1.016	2.286		0.040	0.090	
S1	0.381	1.778		0.015	0.070	

24.13 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form) (TQ)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Package Group: Plastic TQFP						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25mm (0.010") per side. D1 and E1 dimensions including mold mismatch.

2: Dimension "b" does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08mm (0.003")max.

3: This outline conforms to JEDEC MS-026.

PIN COMPATIBILITY

Devices that have the same package type and VDD, VSS and MCLR pin locations are said to be pin compatible. This allows these different devices to operate in the same socket. Compatible devices may only requires minor software modification to allow proper operation in the application socket (ex., PIC16C56 and PIC16C61 devices). Not all devices in the same package size are pin compatible; for example, the PIC16C62 is compatible with the PIC16C63, but not the PIC16C55.

Pin compatibility does not mean that the devices offer the same features. As an example, the PIC16C54 is pin compatible with the PIC16C71, but does not have an A/D converter, weak pull-ups on PORTB, or interrupts.

TABLE F-1: PIN COMPATIBLE DEVICES

Pin Compatible Devices	Package
PIC12C508, PIC12C509, PIC12C671, PIC12C672	8-pin
PIC16C154, PIC16CR154, PIC16C156, PIC16CR156, PIC16C158, PIC16CR158, PIC16C52, PIC16C54, PIC16C54A, PIC16CR54A, PIC16C56, PIC16C58A, PIC16CR58A, PIC16C61, PIC16C554, PIC16C556, PIC16C558 PIC16C620, PIC16C621, PIC16C622 PIC16C641, PIC16C642, PIC16C661, PIC16C662 PIC16C710, PIC16C711, PIC16C715 PIC16F83, PIC16CR83, PIC16F84A, PIC16CR84	18-pin, 20-pin
PIC16C55, PIC16C57, PIC16CR57B	28-pin
PIC16CR62, PIC16C62A, PIC16C63, PIC16CR63, PIC16C66, PIC16C72, PIC16C73A, PIC16C76	28-pin
PIC16CR64, PIC16C64A, PIC16C65A, PIC16CR65, PIC16C67, PIC16C74A, PIC16C77	40-pin
PIC17CR42, PIC17C42A, PIC17C43, PIC17CR43, PIC17C44	40-pin
PIC16C923, PIC16C924	64/68-pin
PIC17C756, PIC17C752	64/68-pin

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